

Test Case	Example	DUT configuration					Result	Comments
		Linux	TI RTOS	Coord	Router	End Device		
Stress test Tiva Coord	stressTest		x	x			Pass	Pass Cnt: x Error Cnt: y ED not tested (see limitations in ReadMe.MD)
	stressTest	x			x			
Stress test Linux Coord	stressTest	x		x			Pass	Pass Cnt: x Error Cnt: y ED not tested (see limitations in ReadMe.MD)
	stressTest	x			x			
	stressTest		x		x			
Command Line	cmdLine	x		x			Pass	
	cmdLine	x			x		Pass	
	cmdLine	x				x	Pass	
	cmdLine		x		x		Pass	
Data Send Receive (Linux Coord)	dataSendRecv	x		x			Pass	
	dataSendRecv	x			x		Pass	
	dataSendRecv	x				x	Pass	
	dataSendRecv		x			x	Pass	
Data Send Receive (TI RTOS Coord)	dataSendRecv		x	x			Pass	
	dataSendRecv	x			x		Pass	
	dataSendRecv	x				x	Pass	
	dataSendRecv	x				x	Pass	
Network Topology (Linux Coord)	nwkTopology	x		x			Pass	
	nwkTopology	x			x		Pass	
	nwkTopology	x				x	Pass	
	nwkTopology		x			x	Pass	

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